



Material Content Data Sheet



Sales Product Name		BTF50060-1TEA		Issued		24. January 2018		
MA#		MA001659016						
Package		PG-TO252-5-11		Weight*		356.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.311	1.21	1.21	12089	12089
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	iron	7439-89-6	0.205	0.06		573	
	non noble metal	copper	7440-50-8	204.243	57.26	57.34	572726	573471
	non noble metal	aluminium	7429-90-5	1.945	0.55	0.55	5455	5455
wire	non noble metal	aluminium	7429-90-5	1.945	0.55	0.55	5455	5455
encapsulation	organic material	carbon black	1333-86-4	1.378	0.39		3863	
	plastics	epoxy resin	-	24.108	6.76		67603	
	inorganic material	silicondioxide	60676-86-0	112.276	31.48	38.63	314838	386304
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14224	14224
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	214	215
glue	plastics	Polyimide	26023-21-2	0.156	0.04	0.04	436	436
solder	non noble metal	tin	7440-31-5	0.056	0.02		156	
	noble metal	silver	7440-22-4	0.070	0.02		195	
	non noble metal	lead	7439-92-1	2.658	0.75	0.79	7455	7806
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com